

WHAT IS CLAIMED IS:

1. A method of manufacturing the semiconductor device comprising:

arranging at least a part of a portion of a lead frame
5 that is to be sealed with a resin, and a portion that is
to become an outer lead, respectively, in a cavity of a metal
mold;

filling a sealing resin into the cavity of said metal
mold, and hardening the sealing resin; and

10 removing a member covering a surface layer region of
the section, to become the outer lead, of said lead frame.

2. The method of manufacturing the semiconductor device
according to claim 1, wherein

15 a plurality of semiconductor device constituent
sections are arranged in a common cavity of said metal mold
on said lead frame.

3. A method of manufacturing the semiconductor device
20 comprising:

fixedly attaching removable members to both sides of
a section, to become an outer lead, of a lead frame;

arranging a section, to be sealed with a resin, of
said lead frame including said removable members in a cavity
25 of a metal mold;

filling a sealing resin into the cavity of said metal mold, and hardening the sealing resin;

forming a groove ranging from a surface of said sealing resin to edges of said removable members; and

- 5 removing a member covering the section to become said outer lead, with the portion in which said groove is formed set as a boundary.

4. The method of manufacturing the semiconductor device
10 according to claim 3, wherein

bonding sheets having removability with respect to the section to become said outer lead are employed as said removable members.

- 15 5. The method of manufacturing the semiconductor device according to claim 3, wherein

spacers detachable from the section to become said outer lead are employed as said removable members.

- 20 6. The method of manufacturing the semiconductor device according to claim 3, wherein

spacers each having a removable bonding surface formed between each spacer and the section to become said outer lead, are employed as said removable members.

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7. The method of manufacturing the semiconductor device according to claim 5, wherein

if said lead frame is arranged in the cavity of said metal mold, said spacers are abutted on inner wall surfaces of the cavity.

8. The method of manufacturing the semiconductor device according to claim 6, wherein

if said lead frame is arranged in the cavity of said metal mold, said spacers are abutted on inner wall surfaces of the cavity.

9. The method of manufacturing the semiconductor device according to claim 3, wherein

a plurality of semiconductor device constituent sections are arranged in a common cavity of said metal mold on said lead frame.

10. A semiconductor device manufactured by:

arranging at least a part of a portion of a lead frame that is to be sealed with a resin, and a portion that is to become an outer lead, respectively, in a cavity of a metal mold;

filling a sealing resin into the cavity of said metal mold, and hardening the sealing resin; and

removing a member covering a surface layer region of the section, to become the outer lead, of said lead frame.

11. A semiconductor device manufactured by:

5 fixedly attaching removable members to both sides of a section, to become an outer lead, of a lead frame;

arranging a section, to be sealed with a resin, of said lead frame including said removable members in a cavity of a metal mold;

10 filling a sealing resin into the cavity of said metal mold, and hardening the sealing resin;

forming a groove ranging from a surface of said sealing resin to edges of said removable members; and

removing a member covering the section to become said
15 outer lead, with the portion in which said groove is formed set as a boundary.